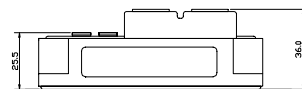
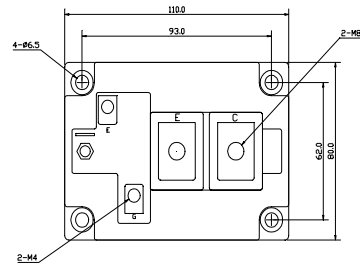
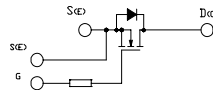


OUTLINE DRAWING
FEATURES

- * Trench Gate MOS FET Module
- * Super Low Rds(ON) 2 milliohms (@560A)
- * With Fast Recovery Source-Drain Diode

TYPICAL APPLICATIONS

- * Chopper Control For FORKLIFTS

Circuit


Approximate Weight : 650g

MAXMUM RATINGS

Ratings		Symbol	PHM5601		Unit
Drain-Source Voltage (V _{GS} =0V)		V _{DSS}	150		V
Gate - Source Voltage		V _{GSS}	+/- 20		V
Continuous Drain Current	Duty=50%	I _D	560 (T _C =25°C)		A
	D.C.		440 (T _C =25°C)		
Pulsed Drain Current		I _{DM}	1,120 T _C =25°C		A
Total Power Dissipation		P _D	1,780 T _C =25°C		W
Operating Junction Temperature Range		T _{JW}	-40 to +150		°C
Storage Temperature Range		T _{stg}	-40 to +125		°C
Isolation Voltage (Terminals to Base AC, 1 min.)		V _{ISO}	2,500		V
Mounting Torque	Module Base to Heatsink	F _{TOR}	3.0		N•m
	Gate Terminals		M4	1.4	
	Bus Bar to Main Terminals		M8	10.5	

ELECTRICAL CHARACTERISTICS (@T_C=25°C unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =V _{DSS} , V _{GS} =0V	-	-	3.2	mA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =+/- 20V, V _{DS} =0V	-	-	3.2	μA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =16mA	1.0	2.0	3.2	V
Static Drain-Source On-Resistance	r _{DS(on)}	V _{GS} =10V, I _D =560A	-	1.6	2.0	m-ohm
Drain-Source On-Voltage	V _{DS(on)}	V _{GS} =10V, I _D =560A	-	1.0	1.2	V
Forward Transconductance	g _{fs}	V _{DS} =15V, I _D =560A	-	-	-	S
Input Capacitance	C _{ies}	V _{DS} =10V, V _{GS} =0V, f=1MHz	-	110	-	nF
Output Capacitance	C _{oss}		-	13	-	nF
Reverse Transfer Capacitance	C _{rss}		-	13	-	nF
Rise Time	t _r	V _{DD} = 80V	-	400	-	ns
Turn-On Delay Time	t _{d(on)}	I _D =280A	-	380	-	
Fall Time	t _f	V _{GS} = -5V, +10V	-	170	-	
Turn-Off Delay Time	t _{d(off)}	R _G = 1.2 ohm	-	1,100	-	

FREE WHEELING DIODES RATINGS & CHARACTERISTICS (T_C=25°C)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Continuous Source Current	I _S	Duty=50%	-	-	560	A
		D.C. (Terminal Temperature=80°C)	-	-	450	
Pulsed Source Current	I _{SM}	-	-	-	1,120	A
Diode Forward Voltage	V _{SD}	I _S =560A	-	1.6	2.0	V
Reverse Recovery Time	t _{rr}	I _S =560A, -dis/dt=1,100A/μs	-	130	-	ns

THERMAL CHARACTERISTICS

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Thermal Resistance, Junction to Case	R _{th(j-c)}		-	-	0.07	°C/W
Thermal Resistance, Case to Heatsink	R _{th(c-h)}	Mounting surface flat, smooth, and greased	-	-	0.035	

PHM5601 OUTLINE DRAWING (Dimensions in mm)

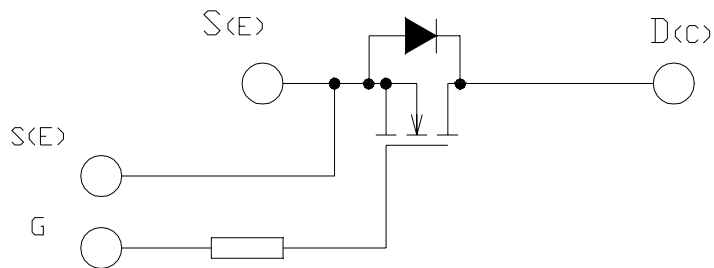
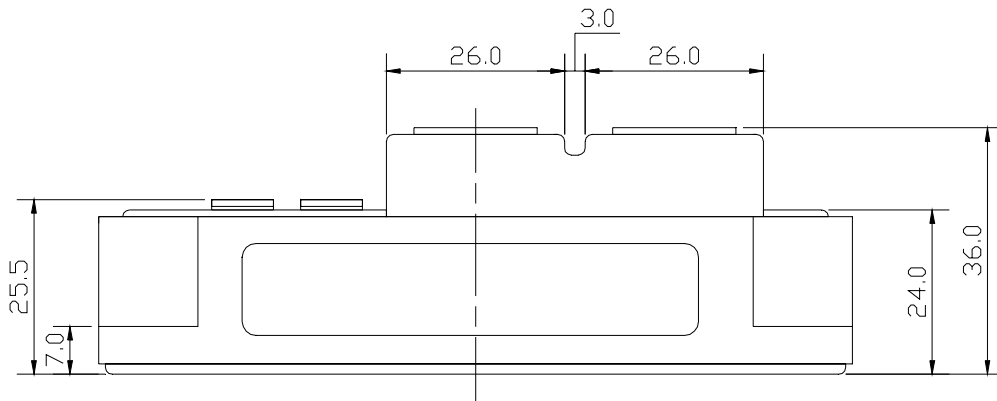
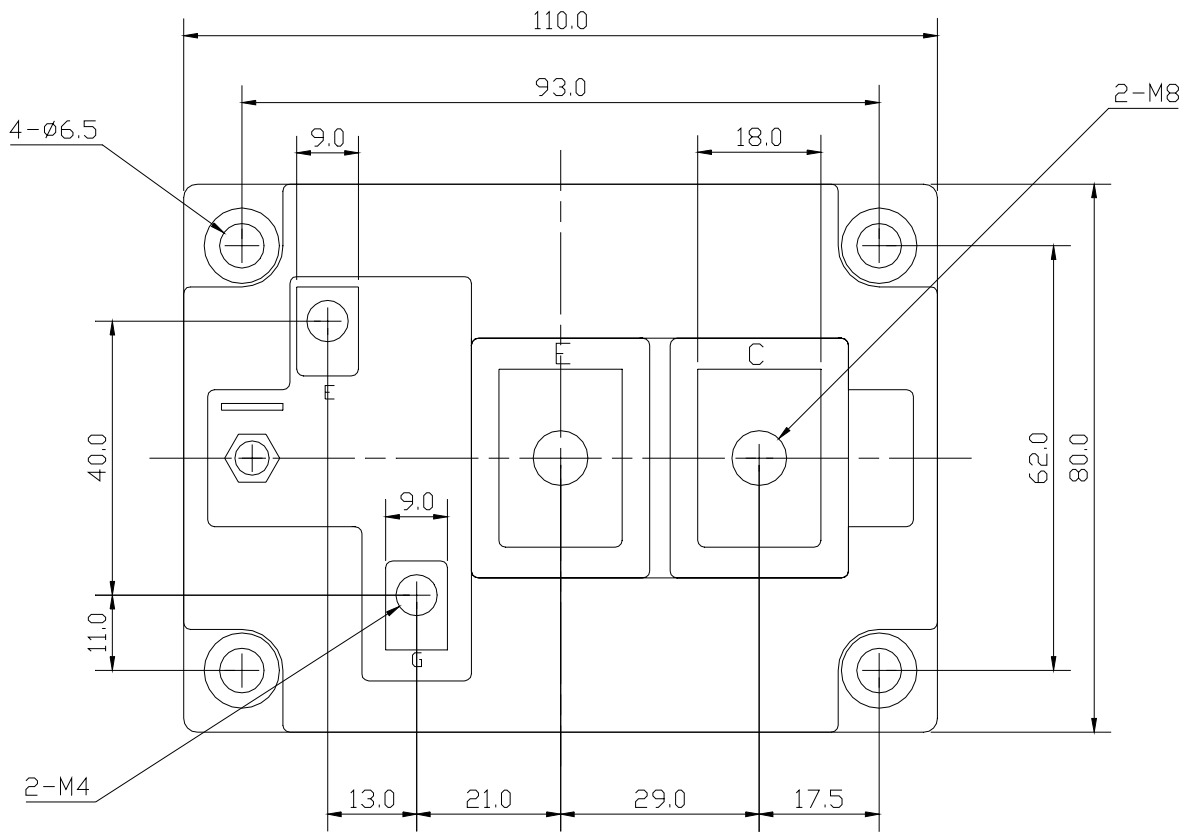


Fig.1- Output Characteristics (Typical)

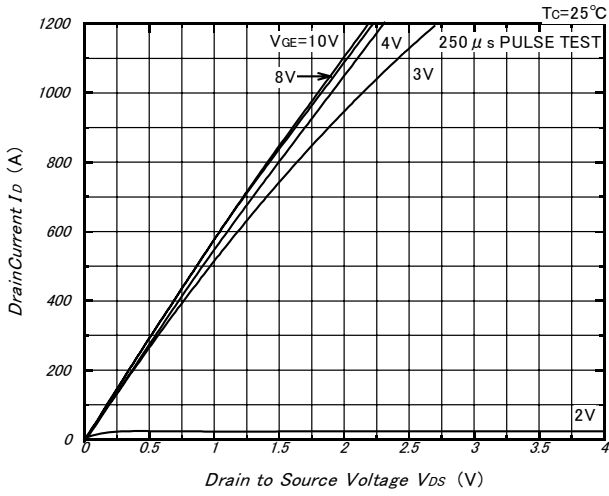


Fig.2- Drain to Source On Voltage vs. Gate to Source Voltage (Typical)

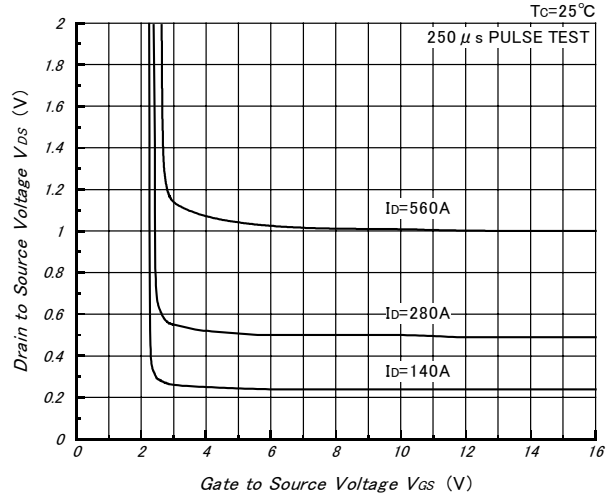


Fig.3- Drain to Source On Voltage vs. Junction Temperature (Typical)

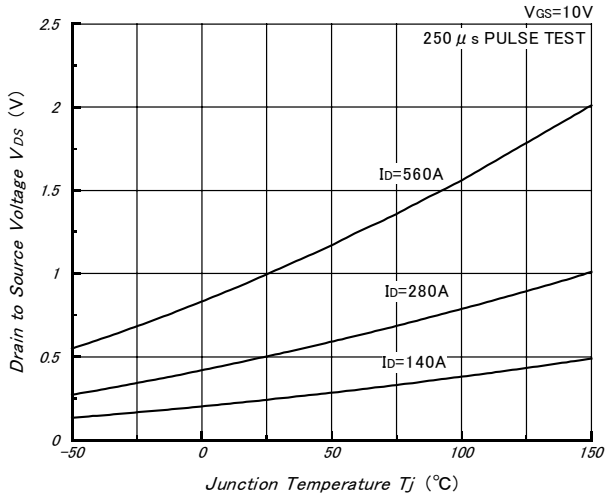


Fig.4- Capacitance vs. Drain to Source Voltage (Typical)

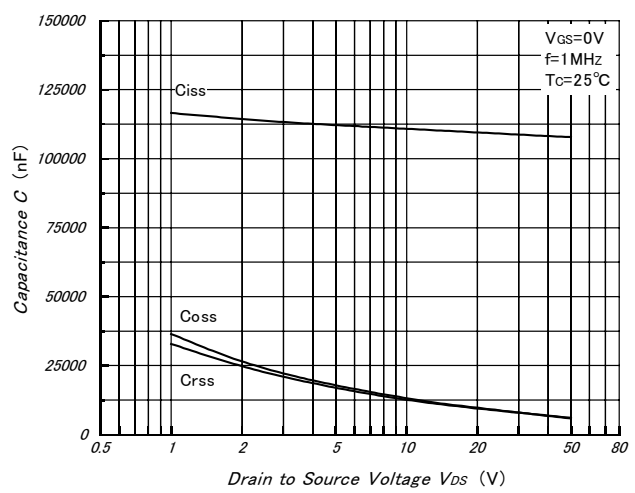


Fig.5- Gate Charge vs. Gate to Source Voltage (Typical)

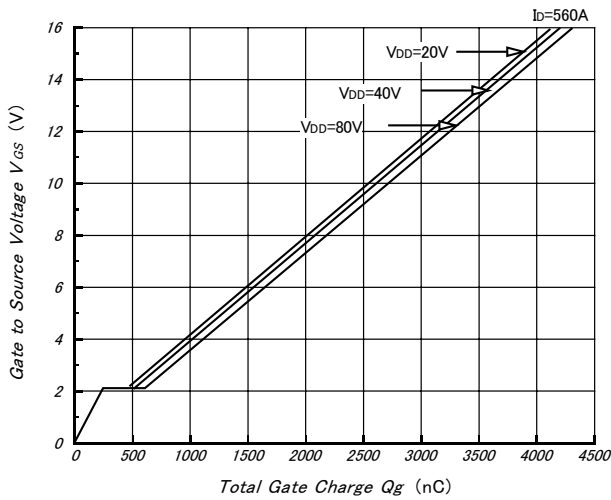


Fig.6- Series Gate Impedance vs. Switching Time (Typical)

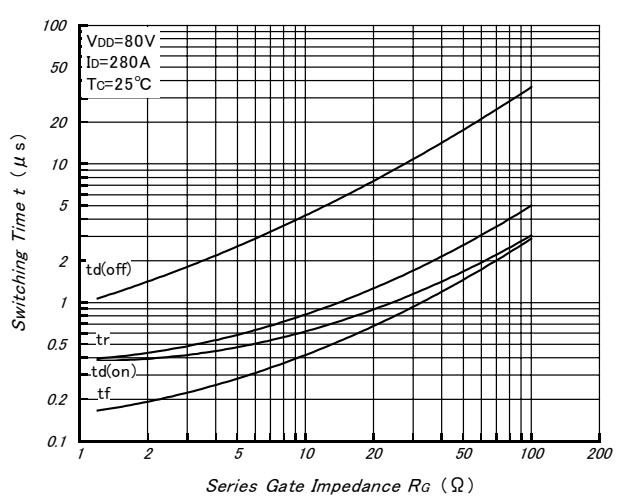


Fig.7- Drain Current vs. Switching Time (Typical)

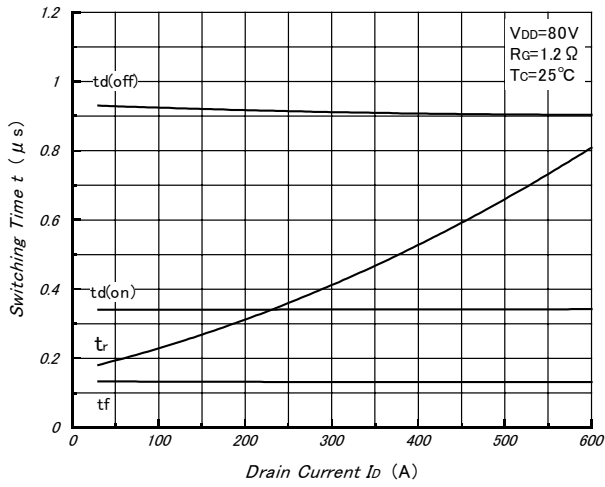


Fig.8- Source to Drain Diode Forward Characteristics (Typical)

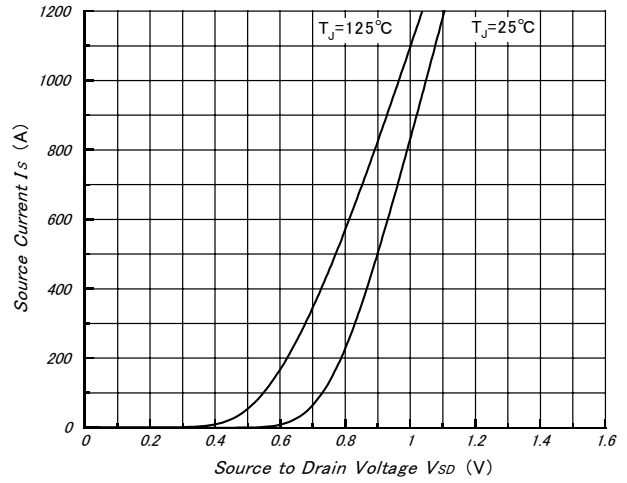


Fig.9- Reverse Recovery Characteristics (Typical)

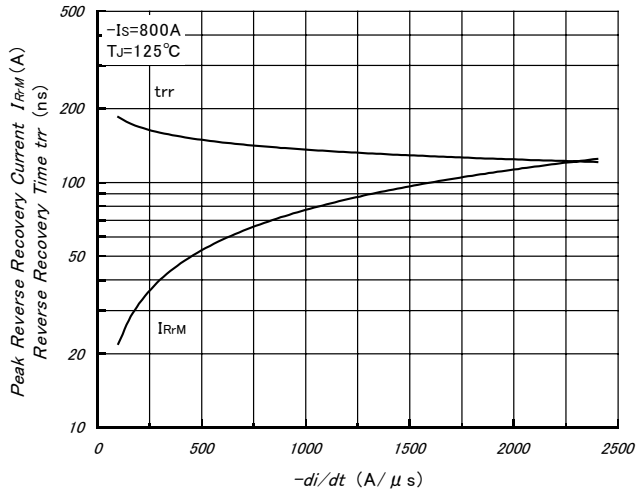


Fig.10- Maximum Transient Thermal Impedance

